

## CBR04C319B2GAC

CBR-SMD RF COG, Ceramic, 3.1 pF, +/-0.1 pF, 200 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



Click [here](#) for the 3D model.

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
B	0.25mm +0.05/-0.1mm

  

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	10000

General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	1.4 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3.1 pF
Capacitance Tolerance	+/-0.1 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	462

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